REMARKS

Claims 1-8 are all the claims pending in the application. Claims 1, 3, 5 and 7 have been amended editorially for improved readability, with no intended change in scope.

In the Office Action, the Examiner has withdrawn the previous rejections of record, and has replaced the same with a single, new rejection under §103. Claims 1-8 now stand rejected under §103 as unpatentable over the admitted prior art in view of the '939 publication to Toshiro.

Apparently, the arguments submitted in response to the previous rejections were successful in convincing the Examiner to withdraw those rejections and perform a new prior art search. However, on review of the new Toshiro reference, it appears that several of the previously-made arguments would still be applicable with respect to this new reference.

Toshiro teaches that insulation deterioration caused by thermal impact and a PCT test (Pressure Cooker Test: Highly Accelerated Temperature and Humidity Stress Test) can be reduced by integrally molding the coil and the bobbin by using a mold material which is the same as the bobbin material. Further, Toshiro teaches that general thermoplastic resins and thermosetting resins can be used commonly as the mold material and the bobbin material. This eliminates cracking caused by the differences in thermal expansion coefficient when different materials are used for the bobbin and the mold material.

Toshiro does not mention any specific environment which the coil will be used, e.g., in an automotive environment, immersed in oil as claimed. Further, there does not appear to be any recognition in Toshiro of the need for special protective measures in such an environment, for example, the prevention of sulfur permeation. Therefore, the Toshiro reference appears to be lacking in several of the same points as the previously-cited references.

As described above, Toshiro does not teach or suggest that sulfur compounds and organosulfur compounds contained in the oil permeate to the insulating layer coated on a copper wire, to reach the surface of the copper wire and act upon the copper wire to form sulfur compounds on the copper wire surface, thereby reducing adhesive strength of the insulating later to the copper wire. Consequently, Toshiro does not teach or suggest that the materials used in

the bobbin and the mold material are to have low permeability to sulfur compounds and organosulfur compounds.

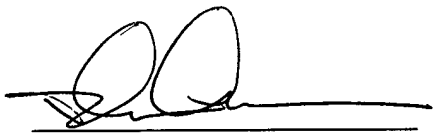
Therefore, there can be no motivation to apply the materials of Toshiro to an insulating layer of the APA for the purpose of reducing deterioration of the adhesive strength of the insulating layer to the copper wire caused by sulfur compounds and organosulfur compounds contained in the oil.

The subject matter of claims 1, 3, 5 and 7 is accordingly patentable over the APA and Toshiro and the rejections thereof under 35 U.S.C. § 103(a) should be withdrawn.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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